

Microfabrication/Microfluidics Facility, Harvard Medical School

PLASMA ETCHER 500 II USER OPERATION

Equipment Operation:

- 1. Turn on the vacuum pump located next to the plasma cleaner.
- 2. Turn the **main power** on (red bottom).
- 3. Open the **vacuum** toggle switch (labeled as **VAC** in front panel), and check the throttle pressure on the display (Wait until the pressure stabilizes between 0.100 Torr t-450 Torr. The pressure should not be oscillating abruptly). Write down this value.
- 4. Open gas 1 toggle switch (oxygen).
- **5.** Adjust and stabilize the pressure at approximately 0.060Torr-0.080Torr difference from the Vacuum pressure obtained previously. Wait approximately 2 mins.
- **6.** Turn on the **RF power** switch and set the power at desired power depending on the process.
- 7. Turn off the **RF power**.
- 8. Turn off gas 1.
- 9. Turn off vacuum.
- 10. Switch to open vent toggle switch.
- 11. Wait until the door can be opened and **TURN OFF THE VENT.**